

Bringing tomorrow's electronics to life



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MRSI Systems (a part of Mycronic Group) is the leading manufacturer of fully automated, high-speed, high-precision, and flexible eutectic and epoxy die bonding systems. We leverage over 40 years of industry expertise in high-accuracy die bonders, active aligners, and fluid dispensers to deliver unparalleled precision and reliability for R&D, NPI, and high-volume manufacturing of photonic devices such as lasers, detectors, modulators, WDM/EML TO-Cans, Optical transceivers, LiDAR, VR/AR, sensors, silicon photonics, co-packaging optics, and optical imaging products. We provide the most flexible assembly solutions for all packaging levels, including chip-on-wafer (CoW), chip-on-carrier (CoC), PCB, and gold-box packaging. Our commitment to excellence ensures we meet our customers' needs with meticulous attention to detail and 24/7 field support. For more information, visit <https://www.mycronic.com/product-areas/die-bonding/>.

Mycronic is a Swedish high-tech company engaged in the development, manufacture and marketing of production equipment with high precision and flexibility requirements for the electronics industry. Mycronic's headquarters are located in Täby, north of Stockholm and the Group has subsidiaries in China, France, Germany, Japan, Mexico, the Netherlands, Singapore, South Korea, United Kingdom, the United States and Vietnam. Mycronic is listed on Nasdaq Stockholm. www.mycronic.com

Specifications are subject to change without notice.

202607_MRSI-705V5

MRSI-705

5 MICRON DIE BONDER

500N
High Force
Available



Patented turret for "on-the-fly" tool change

MRSI Systems has been serving optoelectronic and microelectronic customers for the past 40+ years and understands their requirement to scale efficiently in today's fast-paced marketplace.

Applications are found across a wide range of market segments, such as AI Clusters, Medical, Aerospace, Wireless, Automotive, Sensors, and more.

MRSI's die bonding solutions help our customers to enable just-in-time supply and fast-pace innovations of critical components for high-growth market segments. The ultra-flexible MRSI-705 can be used for R&D prototyping to low/medium volume. With our optional patented turret for “on-the-fly” tool change, high volume can be achieved.

Our family of die bonding solutions are built with the same hardware and software platforms configured to minimize process deviations, reduce NPI cost, and increase ROI for customers with MRSI's long proven product reliability and global customer support.



MRSI-705 Die Bonder Ultimate Flexibility



Assembly Technologies

- Eutectic Bonding
- Epoxy Die Attach
- In-situ UV Bonding
- Flip Chip Assembly
- Thermal Compression Bonding



All-In-One Platform

- Large Configurable Work Area
- Force Control for Advanced Assembly
- Advanced Machine Vision
- Programmable Multi-Color Lighting
- Quality Software, Computer and Motion Control
- Turnkey Integrated Production Lines

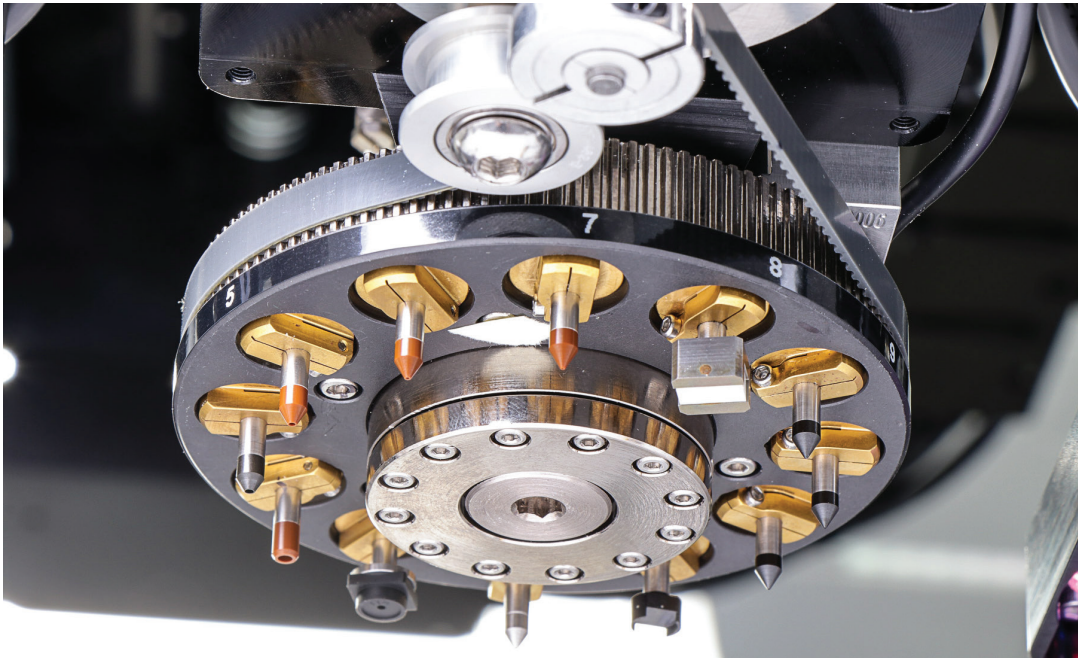
MACHINE PLATFORM	
Gantry and Bond-Head	Solid granite overhead platform supporting gantry and bond-head
XY Motor Type	Zero force, ironless motors with active cooling
X/Y/Z Resolution	0.1µm/0.1µm/0.4µm
Gantry X-axis Travel	495 mm (19.5 inches)
Gantry Y-axis Travel	864 mm (34 inches)
Z Travel	32 mm (1.25 inches)
Z Axis Positioning	Place to force or height
Θ Travel / Θ Resolution	360° / 0.004°



Configuration for Higher Volume

The MRSI-705 offers an optional patented turret for “on-the-fly” tool change to significantly increase the production volume from our machine without sacrificing flexibility. The patented turret has the capacity for 12 tools with zero tool change time.

This leads to increased machine efficiency, higher output and lower manufacturing costs.



Applications

- Microwave Modules
- Photonics Packaging
- RF Power Amplifiers
- Infrared Sensors
- Pressure Sensors
- MEMS Devices
- Semiconductor Packaging
- Hybrid Electronics
- Multichip Modules
- Medical Imaging
- Laser Diode Bonding
- Inkjet and Print Head

